SOD81
hermetically sealed glass package; axial leaded; 2 leads
23 October 2018   **Package information**

1 Package summary

Terminal position code	A (axial)
Package type descriptive code	GALF2
Package type industry code	GALF2
Package style descriptive code	LALF (glass axial (leaded) long form)
Package body material type	L (glass)
Mounting method type	T (through-hole mount)
Issue date	20-06-1997
Manufacturer package code	SOD81

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	3.8	-	mm
package diameter	-	2.15	-	mm
actual quantity of termination	-	2	-	

2   Package outline

Hermetically sealed glass package;
Implotec^TM(1) technology; axial leaded; 2 leads   **SOD81**

DIMENSIONS (mm are the original dimensions)

UNIT	b max.	D max.	G max.	G₁ max.	L min.
mm	0.81	2.15	3.8	5	28

Notes

1. Implotec is a trademark of Philips.
2. The marking band indicates the cathode.

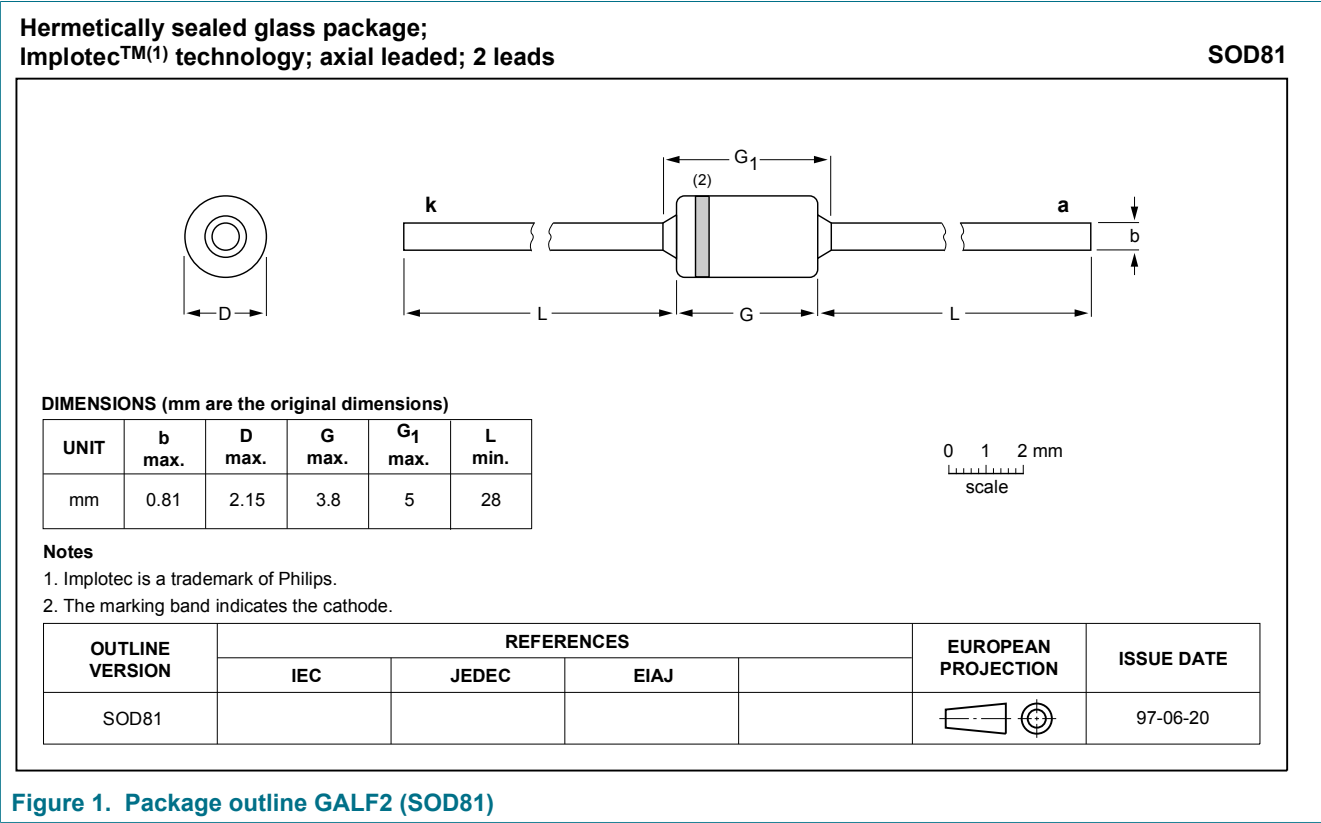| OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOD81						97-06-20

Figure 1. Package outline GALF2 (SOD81)

3 Legal information

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Date of release: 23 October 2018